

PRELIMINARY

DIE BONDER

T-3002-PRO

The **T-3002-PRO** series is Tresky's most flexible die bonding platform. The systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky's products, the PRO incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Together with superior ergonomics the PRO platform is the industry's most sophisticated system in its class and with the new PC software even easier to operate.

True Vertical Technology™

Ultra precise bond-height control

Unique pick-up from wafer

Full PC-Control

The **T-3002-PRO** is equipped with Tresky's die ejector system for pick-up from wafer.

MICRO ASSEMBLY

T-3002-PRO



 **TRESKY**

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Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bonding force control.

APPLICATIONS:

Die Attach, Die Sorting, Flip-Chip, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, AuSn,),

FEATURES AND OPTIONS:

- Programmable Z-Drive with Bonding Force Control

- TRUE VERTICAL TECHNOLOGY™
Z-movement 95mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...

- Flip-Chip Ultra Beam Splitter with multi point alignment
» 1µm placement accuracy



- Interface for all bonding parameter, temperature profile and video imaging of Beam Splitter Optics, Process Inspection Camera

- XY placement stage supporting: Waffle/Gel - Pack -, Substrate - Holder, various Heating Plates

- Pick-up from Wafer with Tresky's patented die ejector system, especially suitable for all kind of Si, GaAs and InP dies down to 30µm thickness

TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (manual)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Bond Force (standard range):	20g - 400g (other force ranges available)
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	±10µm; ±1µm optional (process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

REPRESENTED BY:

HEADQUARTERS

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